APPLICA	BLE STAN	DARD								
	OPERATING TEMPERATURE RANGE		-35 °C TO +85 °C (NOTE1)		STORAGE TEMPERATURE RANGE		GE	-10 °C TO +60 °C (NOTE3)		
RATING	OPERATING HUMIDITY RANGE		40% TO 80% (NOTE2)		STORAGE HUMIDITY RANGE			40% TO 70% (NOTE3)		
	VOLTAGE		050 W 40		APPLICAE CONNECT	PPLICABLE		DF1E-*S-2. 5C		
	CURRENT		AWG20 TO 24: 3A		CONNEC	VOLTAGE				
			AWG26: 2A AWG28: 1A AWG30: 0.5A				-	AC 30V AWG20 TO 22: 3A		
					UL, CSA	CURREN'	Т	AWG24 TO 28: 1A AWG30: 0.5A	١	
			SPEC	IFICAT	IONS	1				
	ГЕМ		TEST METHOD				REQU	IIREMENTS	QT	ΑΊ
	RUCTION	IV/ICLIALI	V AND DV MEACHDING IN	ICTDI IMENIT	- 1400	SOBBING:	TO DI	DAVAJINIO	Х	
MARKING		VISUALLY AND BY MEASURING INSTRUMENT. CONFIRMED VISUALLY.			. ACC	ACCORDING TO DRAWING.				X
	IC CHARA								Χ	^
CONTACT RE			AX, 1 mA(DC OR 1000 F	Hz).	30 n	nΩ MAX.			Х	
MILLIVOLT LEVEL METHOD.		500 1/20			400	Laga Ma Mill				L
INSULATION RESISTANCE		500 V DC.			1000	1000 MΩ MIN.			Χ	_
VOLTAGE F	PROOF	650 V A	C FOR 1 min.		NO	FLASHOV	ER OI	R BREAKDOWN.	Х	_
MECHAN	NICAL CHA	RACTE	RISTICS							
MECHANICAL		30TIMES INSERTIONS AND EXTRACTIONS.				① CONTACT RESISTANCE: $30 \text{ m}\Omega$ MAX.				
OPERATION						② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			Х	-
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE			_	① NO ELECTRICAL DISCONTINUITY OF 1 µs.			Х	
SHOCK		0.75 mm, AT 2 h, FOR 3 DIRECTIONS. 490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES				② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				-
			RECTIONS.						X	_
			ACTERISTICS						1	ı
RAPID CHANGE OF TEMPERATURE					min ② 1	 CONTACT RESISTANCE: 30 mΩ MAX. INSULATION RESISTANCE: 1000 MΩ MIN. NO DAMAGE, CRACK OR LOOSENESS OF PARTS. 				_
DAMP HEAT (STEADY STATE)		EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.			2 I 3 N	① CONTACT RESISTANCE: $30 \text{ m}\Omega$ MAX. ② INSULATION RESISTANCE: $500 \text{ M}\Omega$ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.				_
RESISTANCE TO SOLDERING HEAT		1) AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE, 260 °C FOR IMMERSION, DURATION, 10 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE: 300 °C, SOLDERING TIME: 3 sec. NO STRENGTH ON CONTACT.			TER	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			х	_
SOLDERABILITY			RED AT SOLDER TEMPERATURE, FOR INSERTION DURATION, 5 s.			SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED			Х	_
NOTE2:NO CO NOTE3:APPL BEFO	UDE THE TEMPI ONDENSING. Y TO THE COND RE PCB ON BOA	ERATURE F DITION OF L ARD. AFTI	RISING BY CURRENT. ONG TERM STORAGE FOR U ER PCB BOARD, OPERATING TO DR INTERIM STORAGE DURIN	NUSED PROI TEMPERATUR	DUCTS RE AND		2 3 . W		1	l
COUN			ON OF REVISIONS	1	ESIGNED)		CHECKED	DΑ	TE
<u> </u>	50	. 55.01 110		51		•		CO. (_D	2/1	-
Unless otherwise specified, refer to If			EC 60512.			APPRO		KI. AKIYAMA	15. 0	5. 29
						CHEC		TS. FUKUSHIMA	15. 05. 29	
						DESIG		TS. KUMAZAWA	15.0	
Note OT:Qualification Tast AT:A-			Pourance Test V: Applicable Test			DRAWN DRAWN			MI. SAKIMURA 15. 05. 3 ELC-161951-35-00	
		on Test AT:Assurance Test X:Applicable Test			DRAW ART NO	/ING NO.	DF1E-*P-2. 5DS (35)			,
11/0			CIFICATION SHEET				· · ·		Δ	4 / -
HIROSE		OSE EI	SE ELECTRIC CO., LTD.		ODE NO).	CL541 Z		₫	1/1

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